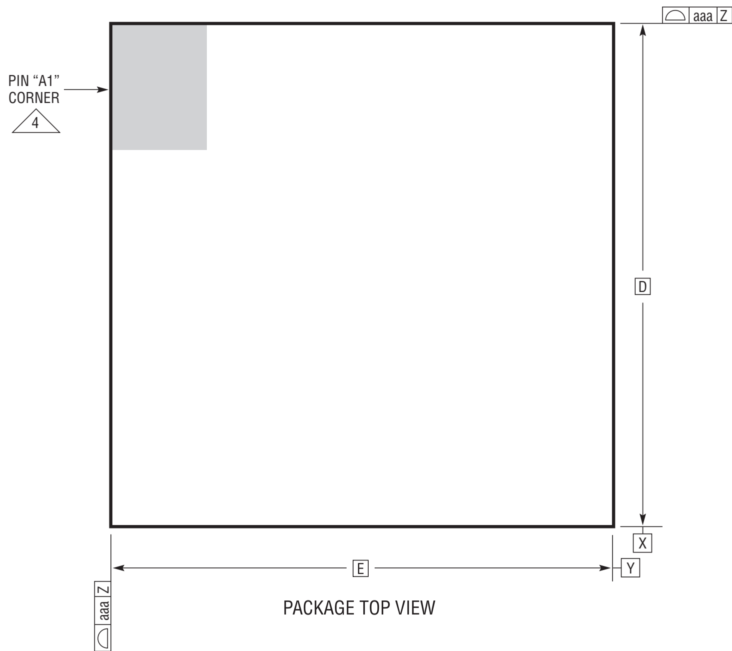
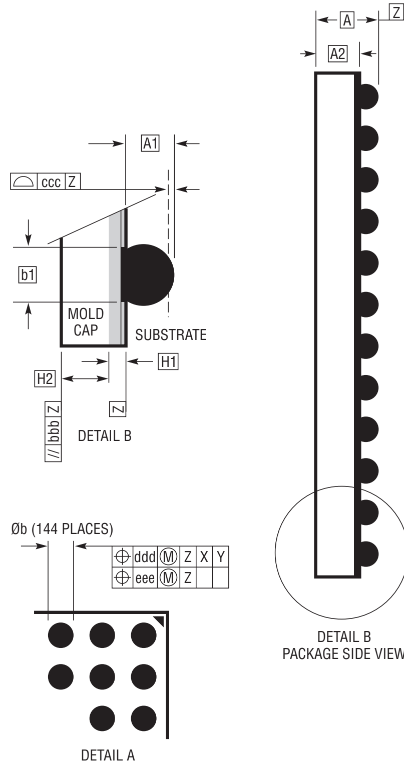
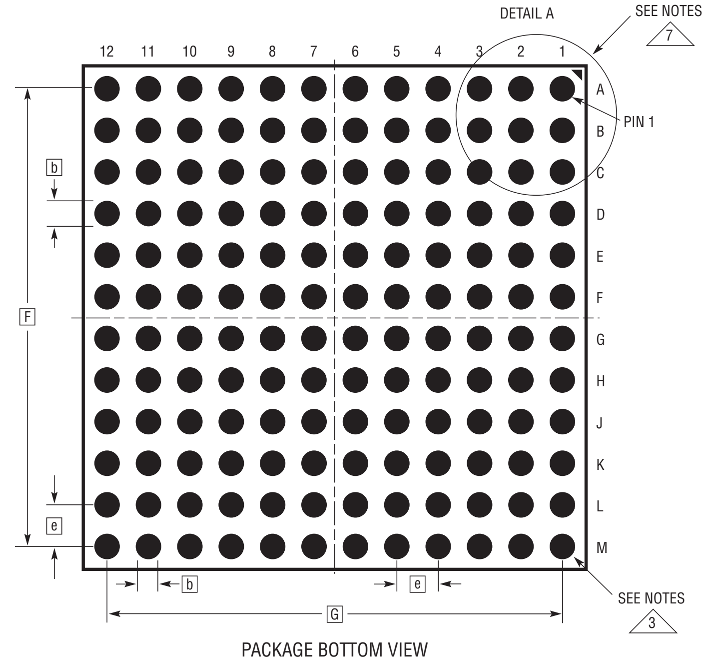
BGA Package
144-Lead (12mm × 12mm × 1.29mm)
(Reference LTC DWG # 05-08-1967 Rev B)
(Y144AH)

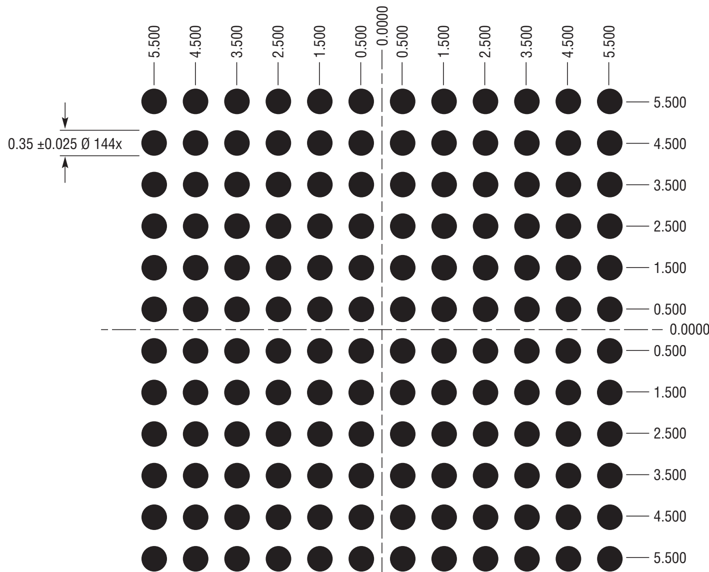


PACKAGE TOP VIEW





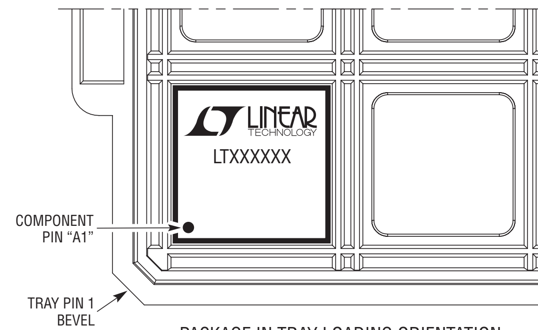
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	1.24	1.29	1.34	
A1	0.27	0.32	0.37	BALL HT
A2	0.92	0.97	1.02	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		12.00		
E		12.00		
e		1.00		
F		11.00		
G		11.00		
H1	0.22	0.27	0.32	SUBSTRATE THK
H2	0.65	0.70	0.75	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.12	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 144				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
7. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 144 1116 REV B